Disco DFG840/841 System

Disco DFG840 and 841 Systems With two-spindle, two-chuck table specifications and a robot arm, the 840 and 841 machines feature a same-cassette return function. The robot arm vacuum ensures that even thin-ground wafers, which are prone to warping, are corrected to the required flatness for trouble free handling. For safety, the DFG841 complies with the EC's CE marking and is based on the SEMI S2-93.

Features

- Handles wafers from 4-8"
- In-feed grinding with wafer rotation
- Two independently adjustable spindles
- Spindle speed - 1000-7000 rpm
- Vertical stroke - 110 mm
- Porous chuck table with vacuum chuck
- 8" diamond grinding wheel
- Two cassettes for loading/unloading
- Planarity accuracy within wafer - 0.0015 mm
- DFG841 complies with the EC's CE marking

Customer Support

Axus Technology provides the installation, warranty, and service support that users depend on for their production and research equipment. Staffed by the most experienced technical teams in the industry, Axus delivers a full range of services to help you manage all your process equipment requirements.

In addition to offering field service, parts, and technical training, Axus Technology's foundry and applications engineers can provide users with process development and engineering services using our fully-equipped applications lab.

We encourage each of our customers to do an on-site inspection of the tool, where they can review the details of the work accomplished, perform a final operational check of the equipment, and participate in the final testing of the tool.

For more information about contract refurbishment services, refurbished tools from Axus Technology, or field service for Disco tools, please contact either Tim St. Marie or Barrie VanDevender at our Chandler, AZ facility.

Facilities

- Dimensions:
  Width: 1,050 mm
  Depth: 2,150 mm
  Height: 1,710 mm
- Electrical: 200V, 3 Phase,50/60Hz
- CDA: 0.5 - 0.8 MPa
- DI Water: 0.2 - 0.3 MPa,
  15 l/min or higher